Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A thermosetting adhesive sheet with electroconductive and thermoconductive properties, comprising:

a) a thermosetting adhesive sheet having two major surfaces, composed of a thermosetting adhesive composition comprising an ethylene-glycidyl (meth)acrylate copolymer and a rosin, said rosin containing a carboxyl group, where crosslinking is formed between the ethylene of said copolymer by electron beam radiation, and having at least one through-opening region formed at a prescribed location, ~~and~~

b) low melting point solder placed within at least one through-opening region formed at the prescribed location, and

c) molten bonding between the solder and the adhesive composition.

2-5. (Cancelled)

6. (New) A thermosetting adhesive sheet according to claim 1 wherein the melting point of the solder is below about 120°C.

7. (New) A thermosetting adhesive sheet with electroconductive and thermoconductive properties, comprising:

(a) a thermosetting adhesive sheet that is a solid at room temperature but can be thermo-compression bonded at temperatures of about 100 to about 200°C, and having a through-opening region formed at a prescribed location,

(b) low melting point solder placed within at least one-through- opening region formed at the prescribed location, and

(c) molten bonding between the solder and the adhesive composition.

8. (New) A thermosetting adhesive sheet according to claim 7 wherein the melting point of the solder is below about 120°C.

9. (New) A method for using the thermosetting adhesive sheet according to claim 1 comprising:

Forming a laminate structure having a first adherend and a second adherend and an adhesive layer between the two adherend layers, and

Subjecting the laminate to a thermocompression bonding operation at a temperature of about 120 to about 300°C and a pressure of about 0.1 to about 100 kg/cm2.

10. (New) A method for using the thermosetting adhesive sheet according to claim 7 comprising:

Forming a laminate structure having a first adherend and a second adherend and an adhesive layer between the two adherend layers, and

Subjecting the laminate to a thermocompression bonding operation at a temperature of about 120 to about 300°C and a pressure of about 0.1 to about 100 kg/cm2.